

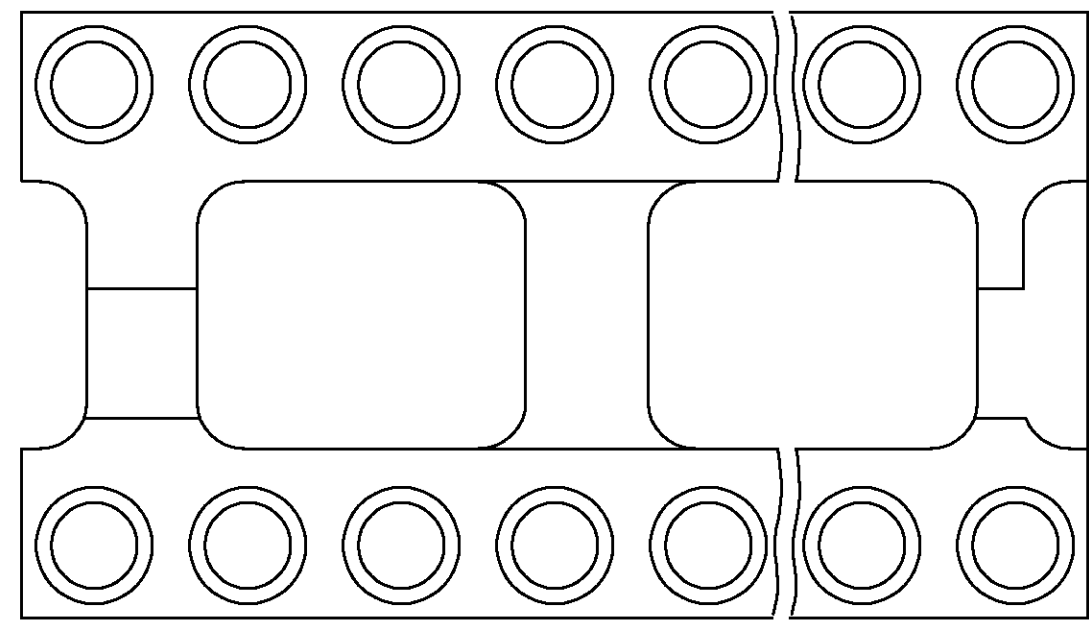


FIG. 1

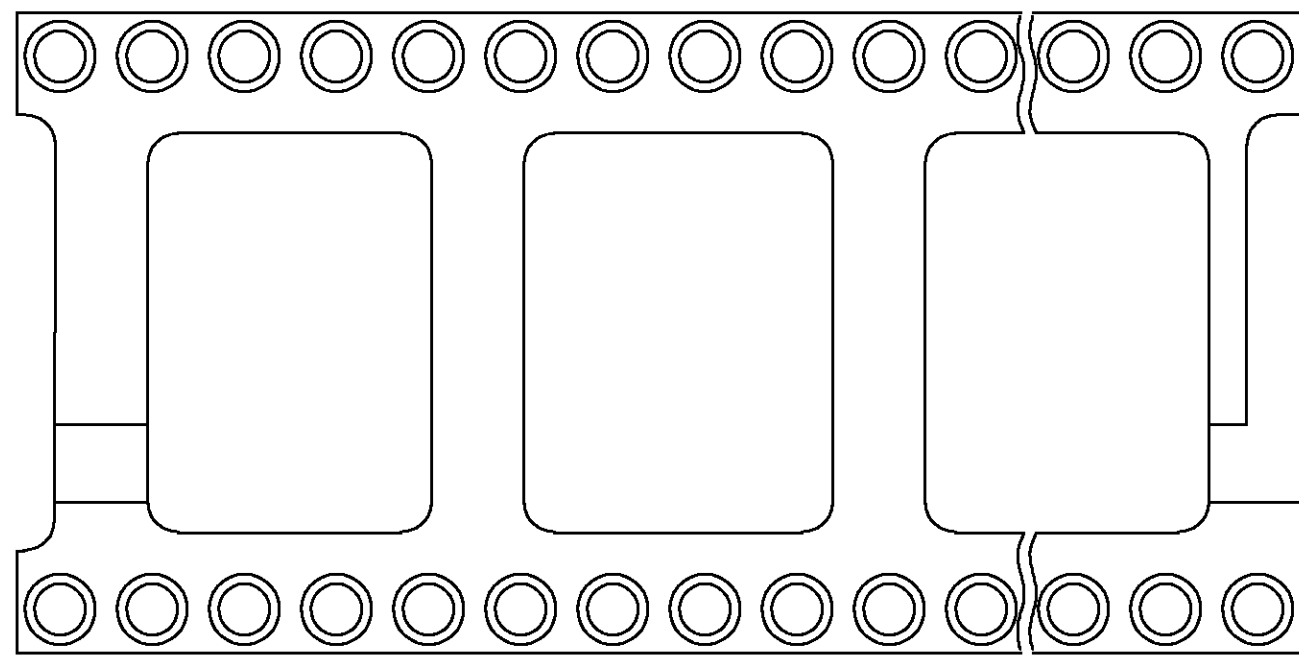


FIG. 2

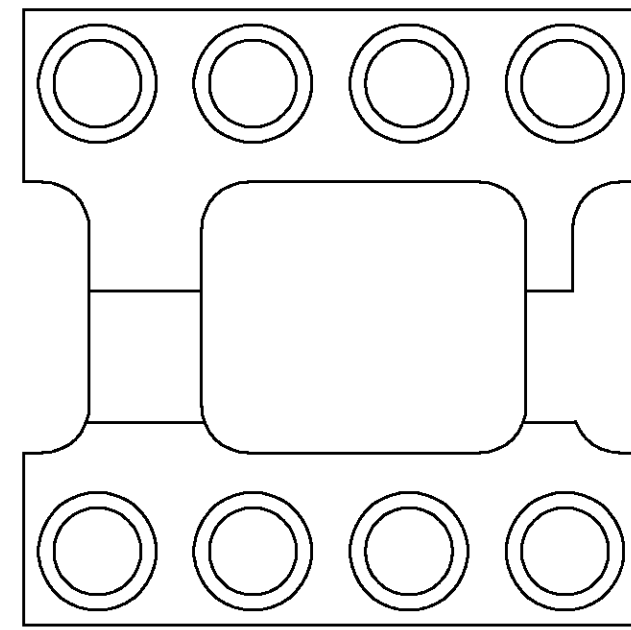
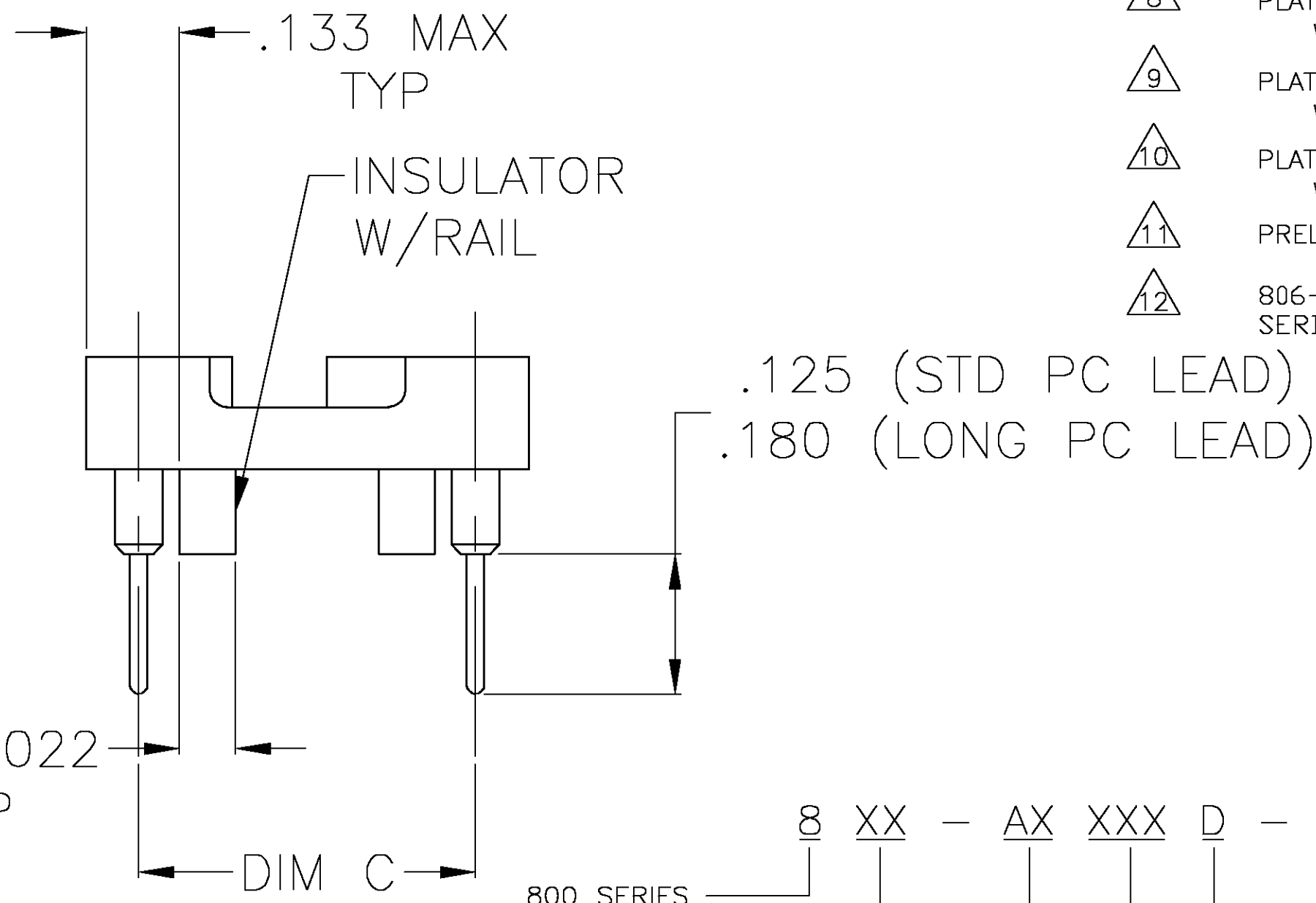
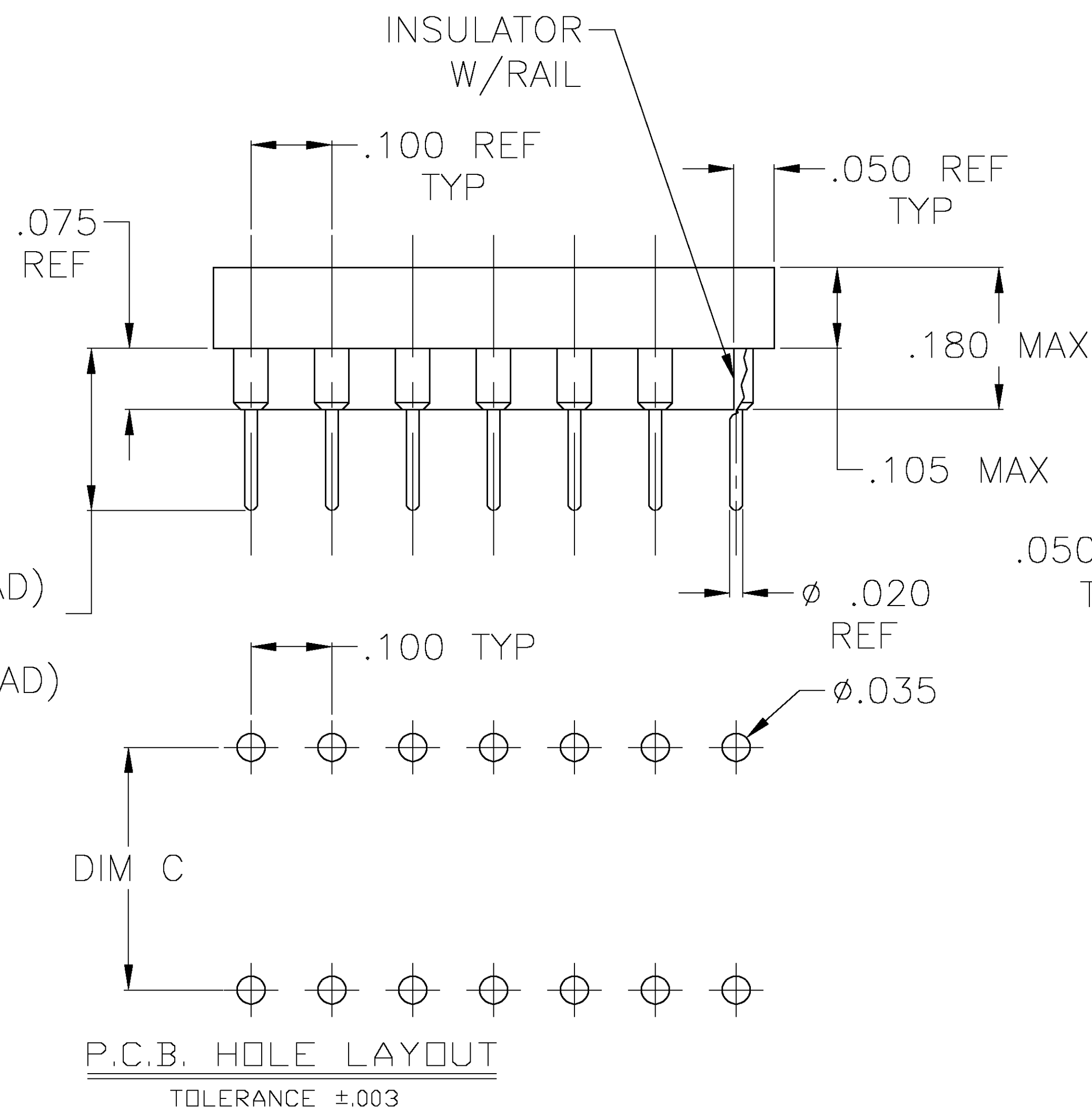
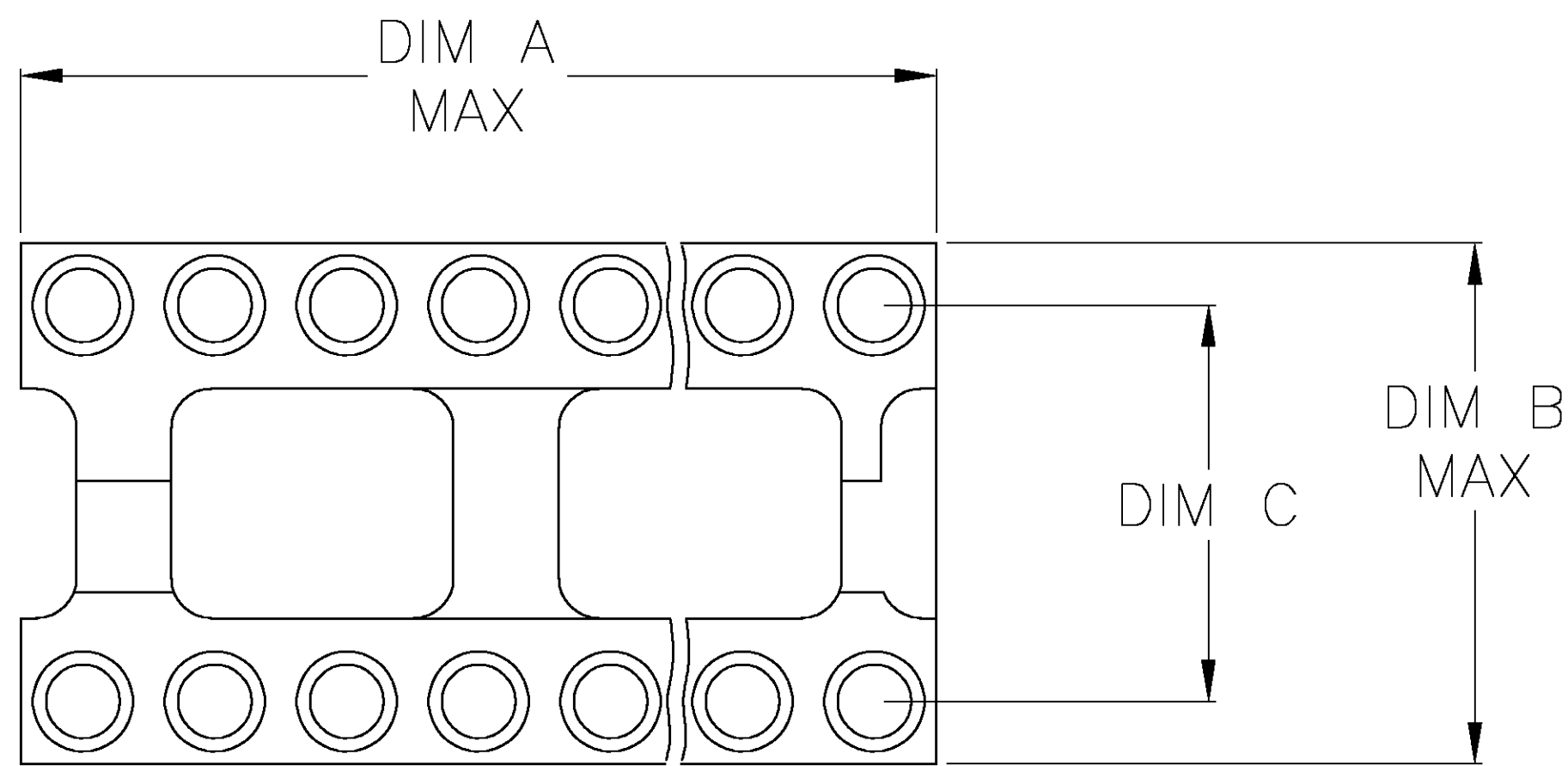


FIG. 3
(8 POS ONLY)



- 1 MATERIALS:
INSULATOR: POLYESTER, UL RATED 94V-0
CONTACT:
800 & 1800 SERIES CONTACT: 4 BEAM, COPPER ALLOY, MACHINED (PREMIUM VERSION) OR FORMED (ECONOMY VERSION, WITH SUFFIX -ES OR -ESL).
800 SERIES HIGH RETENTION CONTACT: 4 BEAM, COPPER ALLOY, MACHINED.
1000 SERIES CONTACT: 6 BEAM, COPPER ALLOY, MACHINED (LOW INSERTION FORCE SERIES)
SLEEVE- ALL SERIES: COPPER ALLOY, FORMED
- 2 ELECTRICAL:
CONTACT RESISTANCE: 10 MILLIOHMS MAX
CONTACT RATING: 3 AMPS
CAPACITANCE: 1.0 pF PER MIL-STD-202, METHOD 305
INSULATION RESISTANCE: 5000 OHMS MIN @ 500 VDC PER MIL-STD-1344, METHOD 3003.1
DIELECTRIC WITHSTANDING VOLTAGE: 1000 VOLTS (RMS) PER MIL-STD-1344, METHOD 3001.1
- 3 MECHANICAL:
AFTER INSERTION FORCE: 37 GRAMS AVG (6 BEAM CONTACT) 134 GRAMS AVG (4 BEAM PREMIUM) 179 GRAMS AVG (4 BEAM ECONOMY) AND 334 GRAMS AVG (HIGH RETENTION)
AFTER WITHDRAWAL FORCE: 15 GRAMS AVG (6 BEAM CONTACT) 63 GRAMS AVG (4 BEAM PREMIUM OR ECONOMY) AND 245 GRAMS AVG (HIGH RETENTION)
- 4 ENVIRONMENTAL:
OPERATING TEMPERATURE: -55°C TO -105°C
- 5 PLATING: 25μ" MIN GOLD OVER 50μ" MIN NICKEL CONTACT WITH 5μ" MIN GOLD OVER 50μ" MIN NICKEL SLEEVE.
- 6 PLATING: 25μ" MIN GOLD OVER 50μ" MIN NICKEL CONTACT WITH 80μ" MIN TIN-LEAD OVER 50μ" MIN COPPER SLEEVE.
- 7 PLATING: 80μ" MIN TIN-LEAD OVER 75μ" MIN COPPER CONTACT WITH 180μ" MIN TIN-LEAD OVER 75μ" MIN NICKEL SLEEVE.
- 8 PLATING: 5μ" MIN GOLD FLASH OVER 50μ" MIN NICKEL CONTACT WITH 5μ" MIN GOLD FLASH OVER 50μ" MIN NICKEL SLEEVE.
- 9 PLATING: 5μ" MIN GOLD FLASH OVER 50μ" MIN NICKEL CONTACT WITH 80μ" MIN TIN-LEAD OVER 50μ" MIN COPPER SLEEVE.
- 10 PLATING: 7.5μ" MIN GOLD OVER 50μ" MIN NICKEL CONTACT WITH 80μ" MIN TIN-LEAD OVER 50μ" MIN COPPER SLEEVE.
- 11 PRELIMINARY PART - NOT RELEASED FOR PRODUCTION.
- 12 806-AGXXD-XXX SERIES IS SUPERSEDED BY 506-AGXXD-XXX SERIES (REFER TO CUSTOMER DRAWING 1437532-2)

8 XX - AX XXX D - XXX
POSITIONS

BLANK = MACHINED CONTACT
ES = FORMED CONTACT, GOLD PLATE, NOTE 1
ESL = FORMED CONTACT, LOW GOLD PLATE, 5μIN MAX

D = PC TAIL STANDARD

LSG STYLE AND TAIL CONFIGURATION

AG = INSULATOR
AR = INSULATOR WITH RAILS
(ALMOST RUN THE LENGTH UNDER THE INSULATOR INSIDE THE CONTACT ROWS, .075 REF HIGH & .045 REF WIDE)

THIS DRAWING IS A CONTROLLED DOCUMENT.		DIN R BROWN 06MAY04	tyco <i>Electronics</i>	Tyco Electronics Corporation Harrisburg, Pa 17105-3608	
DIMENSIONS: INCHES		CHK K WRIGHT 06MAY04		NAME	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD K WRIGHT 06MAY04	PRODUCT SPEC —		DIP SOCKET, 800 SERIES
0 P/LC ± —		APPLICATION SPEC			
1 P/LC ± —		SIZE		CAGE CODE	
2 P/LC ± —		WEIGHT		DRAWING NO	
3 P/LC ± .005		CUSTOMER DRAWING		SCALE 1:1	
4 P/LC ± —		SHEET 1 of 4		REV A	
ANGLES ± —		RESTRICTED TO			
FINISH					

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